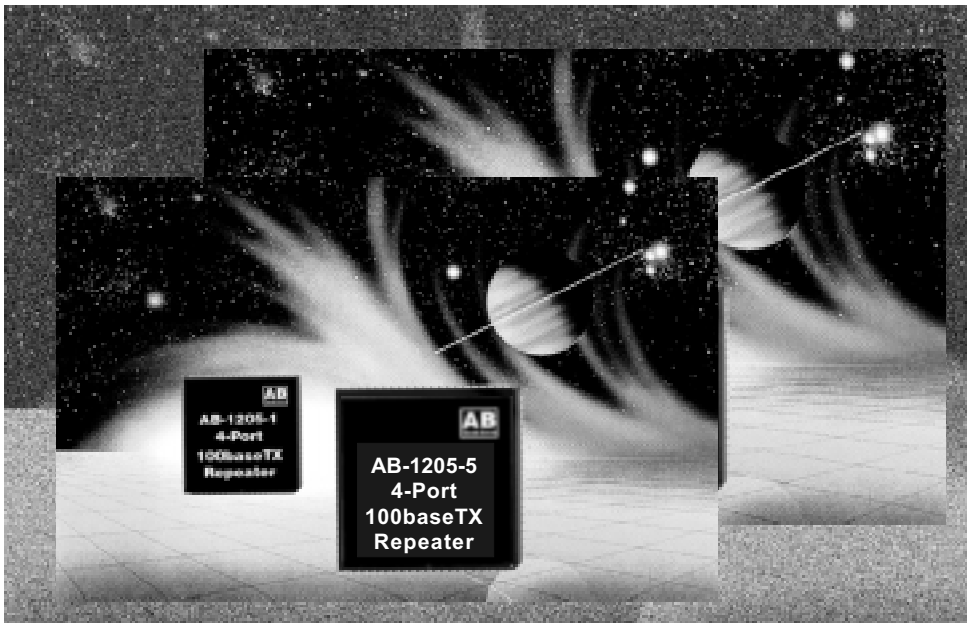




# AB-1205-5

## 4 Port Cascadeable 100base and ATM Repeater Hub



## *Product Specification*

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## **AB Semicon AB1205-5**

100base and ATM  
Repeater Hub  
Product Specification

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# AB-1205-5

## 100base and ATM 4 Port Repeater

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Features:

- \* 4 ports for or AMD's FDDI chip sets and GEC's NWK914
  - \* Local bi-directional high-speed bus for daisy chaining
  - \* Compatible with 100base TX, T4 and T6
  - \* Compatible with 100base VG
  - \* 80 pin PQFP package
  - \* Low Power C-Mos Technology 0.8micron
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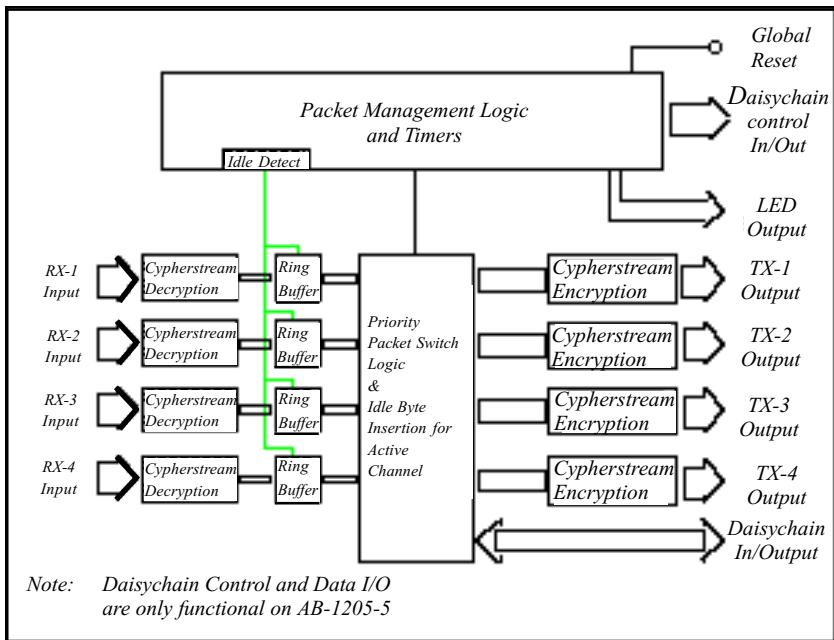
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## INTRODUCTION

This repeater chip allows the connection of an AMD 79865 and 79866 chipset together with NSM DP83223 as the Physical Layer chip as well as being able to use the GEC NWK 914 or AB Semicon AB10100PHY which can replace the AMD and National chip set giving a maximum in flexibility. It can process 4 ports simultaneously in half duplex. The encryption and decryption circuit is built into each of the channels. A local bus allows daisy chaining of any number of devices.

### Chip Structure

The chip contains four high-speed 5bit channels and the control logic for the physical layer interface. Each channel has its own encryption and decryption circuit for circuit simplicity and reduced EMI. Error arbitration logic and collision detection which is also available on output pins on the chip which are capable of driving LEDs directly. There are additional LED outputs to indicate TX or RX data.



**Figure 1**  
**Functional Block Diagram**

## APPLICATIONS

The chip can be used in many different applications where random encryption and decryption is required to achieve a semi spread spectrum use of copper wire to reduce RFI emitted from the cable. It is most powerful for repeater devices such as 4, 8 or 16 port or any multiple of 4 ports, HUB devices. Such applications include 100baseTX repeaters.

Figure 2 gives an overview of low cost repeater applications for which this chip is suitable. Such a repeater can be used in Workgroup or Server-based environments. The data is fully transparently distributed through the Network.

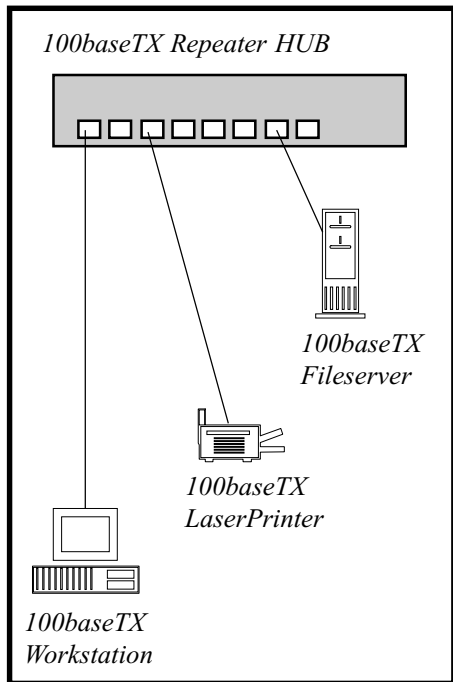


Figure 2

## EXAMPLE for a 4 Port Repeater

Figure 3 shows a 4 port repeater with an extension connector to daisychain any number of 4 port repeaters.

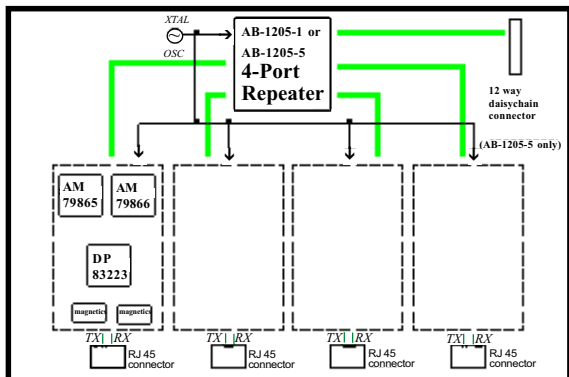


Figure 3

**Interconnection of AB1205-5 and AB10100PHY Physical Layer**

The diagram below shows how the signals between AB1205-5 and AB10100PHY are interconnected for a single port. This interconnection is repeated for the remaining 3 ports, please also refer to the AB10100PHY Product Specification.

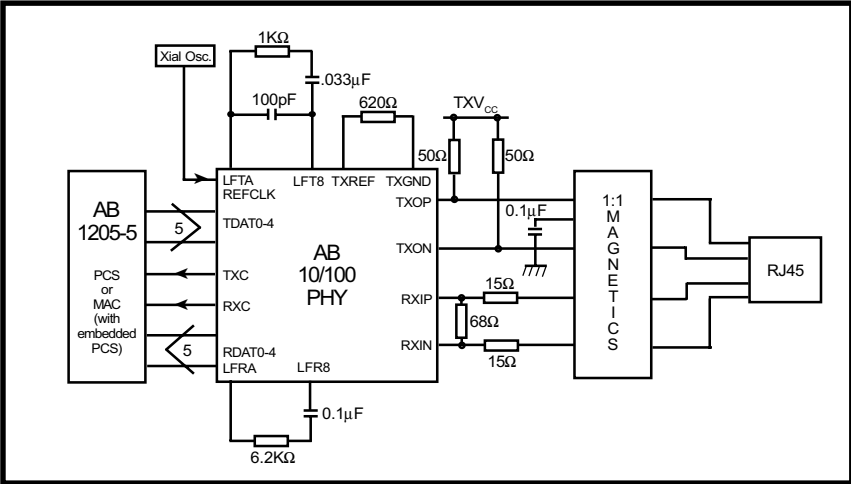
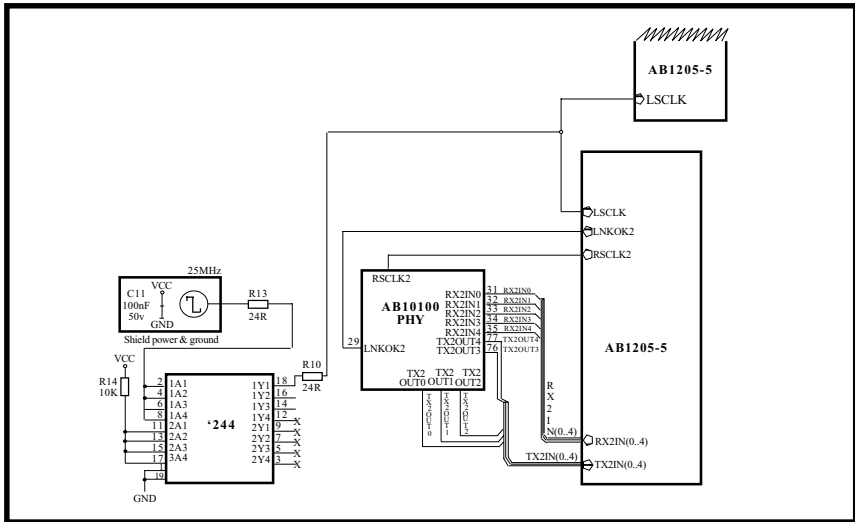


Fig 6. Connection of AB10/100PHY to AB1205-5

## Clock Distribution Circuit

The following diagram shows how the clock is distributed. To assure that the clock is arriving at the same time on all channels, a '244 is used to re-shape the clock signal for each channel.



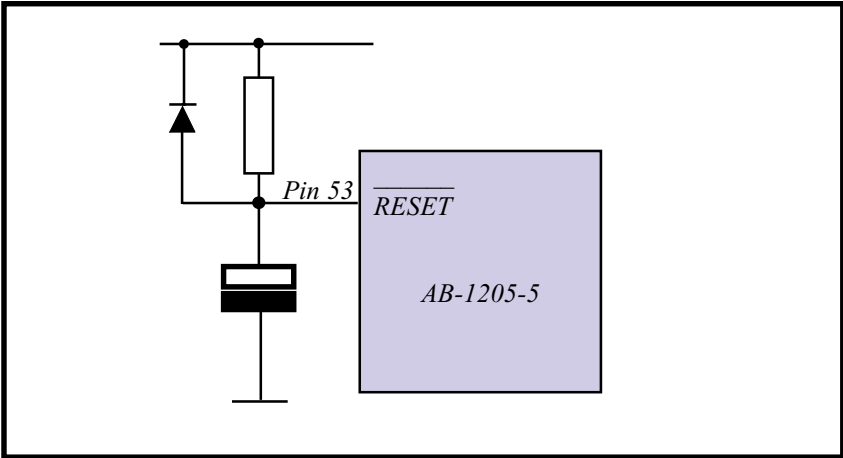
*Diagram showing clock distribution*

Note: When daisychaining the AB1205-5 the remaining buffers of the '244 may be used to re-generate the clock signal.

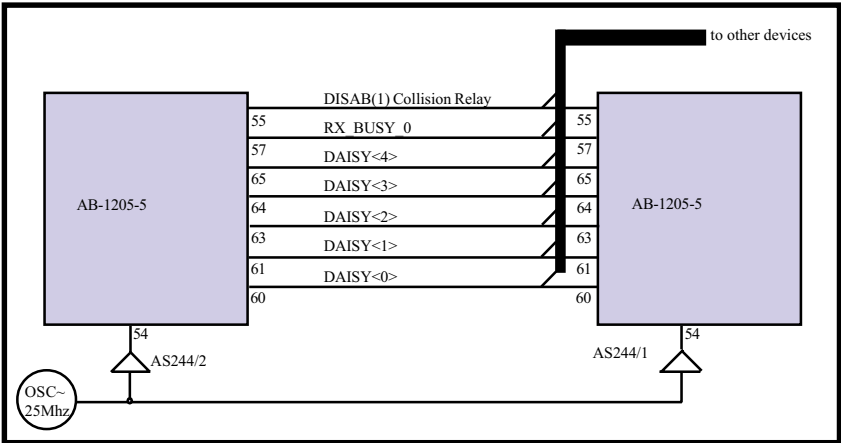
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### Reset circuitry for AB-1205-5

The following diagram shows the reset circuit for the AB-1205-5 four port and cascadeable hub chip.



*Reset Circuit for AB-1205-5*



*Daisy chaining the AB-1205-5*



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## Thermal Characteristics for AB1205-5

This device is supplied in a plastic Quad Flat Pack with a pin count of 80. In this configuration, it has a thermal resistance ( $\theta_{JA}$  - Junction-to-Ambient Measurement) of 85 °C/W in an Alloy 42 Lead Frame with a value of 68 °C/W in a Copper Lead Frame.

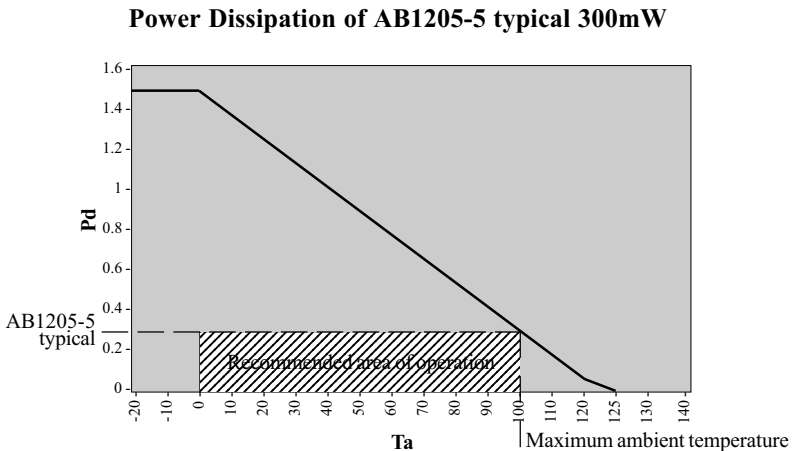
As this device is currently supplied in the Alloy Lead Frame, only that figure has been used in the following calculations.

The Power Dissipation ( $P_d$ ) of the device is calculated as follows:

$$P_d + \frac{T_j - T_A}{\theta_{JA}}$$

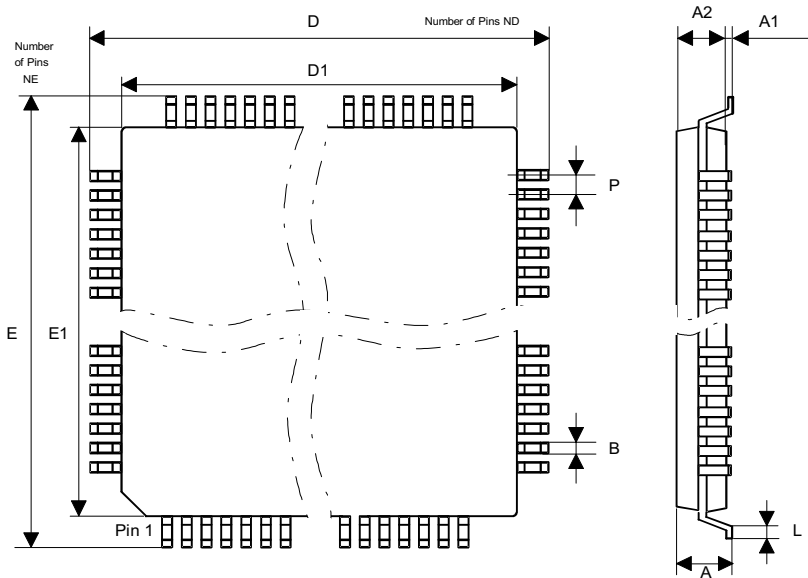
Thus the Power Dissipation is 1.2 Watts at an ambient of 25 °C and 650 mW at 70 °C.

The following plot shows the variation of Power Dissipation with ambient:



A value of  $T_j$  max of 125 °C was used. The range of  $T_j$  is -40 to 125 °C.

# Packaging information



80 ◆ LEAD			
	MIN.	NOM.	MAX.
A	2.82	3.07	3.32
A1	0.25	0.35	0.45
A2	2.57	2.72	287
D	23.00	23.20	23.40
D1	19.90	20.00	20.10
E	17.00	17.20	17.40
E1	13.90	14.00	14.10
L	0.65	0.75	0.95
P		0.80	
B	0.25	0.35	0.45
ND		24	
NE		16	

## I/O Pin Assignment

<i>Pin ID</i>	<i>Signal</i>	<i>Designator</i>
1	GND	Ground
2	NC	
3	NC	
4	Output	TX3_OUT3
5	Output	TX3_OUT4
6	Output	TX4_OUT0
7	Vcc	Power
8	Output	TX4_OUT1
9	Output	TX4_OUT2
10	Output	TX4_OUT3
11	Output	TX4_OUT4
12	Output	-LINK4-(LED)
13	Output	-LED3-(LED)
14	Output	-LINK2-(LED)
15	Output	-LINK1-(LED)
16	Output	-REC4-(LED)
17	Output	-REC3-(LED)
18	Output	-REC2-(LED)
19	GND	Ground
20	Output	-REC1-(LED)
21	Input	LINKOK1
22	Input	RSCLK1
23	Vcc	Power
24	Input	RX1_IN0
25	Input	RX1_IN1

## I/O Pin Assignment

<i>Pin ID</i>	<i>Signal</i>	<i>Designator</i>
26	<i>Input</i>	<i>RX1_IN2</i>
27	<i>Input</i>	<i>RX1_IN3</i>
28	<i>Input</i>	<i>RX1_IN4</i>
29	<i>Input</i>	<i>LINKOK2</i>
30	<i>Input</i>	<i>RSCLK2</i>
31	<i>Input</i>	<i>RX2_IN0</i>
32	<i>Input</i>	<i>RX2_IN1</i>
33	<i>Input</i>	<i>RX2_IN2</i>
34	<i>Input</i>	<i>RX2_IN3</i>
35	<i>Input</i>	<i>RX2_IN4</i>
36	<i>Input</i>	<i>-LINKOK3-</i>
37	<i>Input</i>	<i>-RSCLK3-</i>
38	<i>Input</i>	<i>RX3IN0</i>
39	<i>Input</i>	<i>RX3IN1</i>
40	<i>Input</i>	<i>RX3IN2</i>
41	<i>Input</i>	<i>RX3IN3</i>
42	<i>Vdd</i>	<i>Power (Core)</i>
43	<i>GND</i>	<i>Ground</i>
44	<i>Input</i>	<i>RX3IN4</i>
45	<i>Input</i>	<i>-LINKOK4-</i>
46	<i>GNDc</i>	<i>Ground (Core)</i>
47	<i>Input</i>	<i>RSCLK4</i>
48	<i>Input</i>	<i>RX4_IN0</i>
49	<i>Input</i>	<i>RX4_IN1</i>
50	<i>Input</i>	<i>RX4_IN2</i>

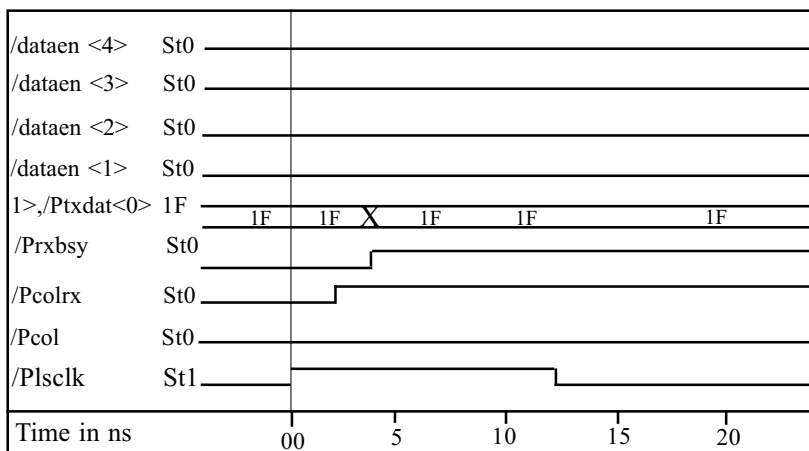
## I/O Pin Assignment

<i>Pin ID</i>	<i>Signal</i>	<i>Designator</i>
51	<i>Input</i>	<i>RX4_IN3</i>
52	<i>Input</i>	<i>RX4_IN4</i>
53	<i>Input</i>	<i>-RESET-</i>
54	<i>Input</i>	<i>LSCLK</i>
55	<i>Output</i>	<i>-DISAB1-(Col)</i>
56	<i>N/C</i>	<i>N/C</i>
57	<i>Input/Output</i>	<i>RX_BUSY_0</i>
58	<i>Vcc</i>	<i>Power</i>
59	<i>GND</i>	<i>Ground</i>
60	<i>Input/Output</i>	<i>DAISY 0</i>
61	<i>Input/Output</i>	<i>DAISY 1</i>
62	<i>Vcc</i>	<i>Power</i>
63	<i>Input/Output</i>	<i>DAISY 2</i>
64	<i>Input/Output</i>	<i>DAISY 3</i>
65	<i>Input/Output</i>	<i>DAISY 4</i>
66	<i>GND</i>	<i>Ground</i>
67	<i>Output</i>	<i>TX1_OUT0</i>
68	<i>Output</i>	<i>TX1_OUT1</i>
69	<i>Output</i>	<i>TX1_OUT2</i>
70	<i>Output</i>	<i>TX1_OUT3</i>
71	<i>Output</i>	<i>TX1_OUT4</i>
72	<i>Output</i>	<i>TX2_OUT0</i>
73	<i>Output</i>	<i>TX2_OUT1</i>
74	<i>Vcc</i>	<i>Power</i>
75	<i>Output</i>	<i>TX2_OUT2</i>

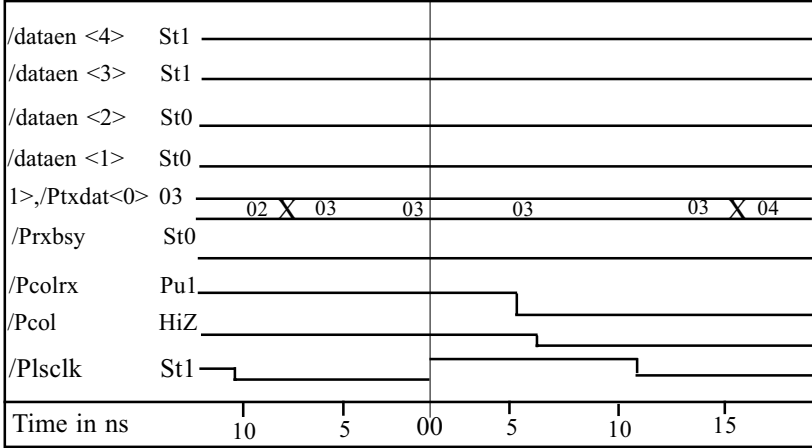
## I/O Pin Assignment

<i>Pin ID</i>	<i>Signal</i>	<i>Designator</i>
76	<i>Output</i>	<i>TX2_OUT3</i>
77	<i>Output</i>	<i>TX2_OUT4</i>
78	<i>Output</i>	<i>TX3_OUT0</i>
79	<i>Output</i>	<i>TX3_OUT1</i>
80	<i>Output</i>	<i>TX3_OUT2</i>

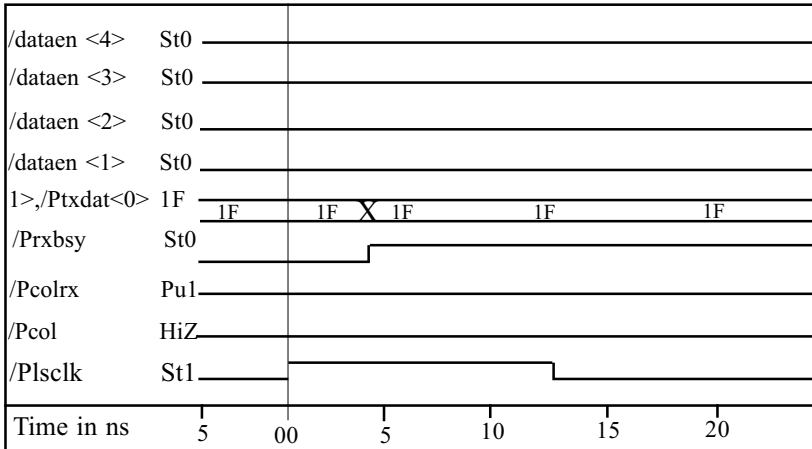
### Clock to Pcolrx inactive at end of collided packet



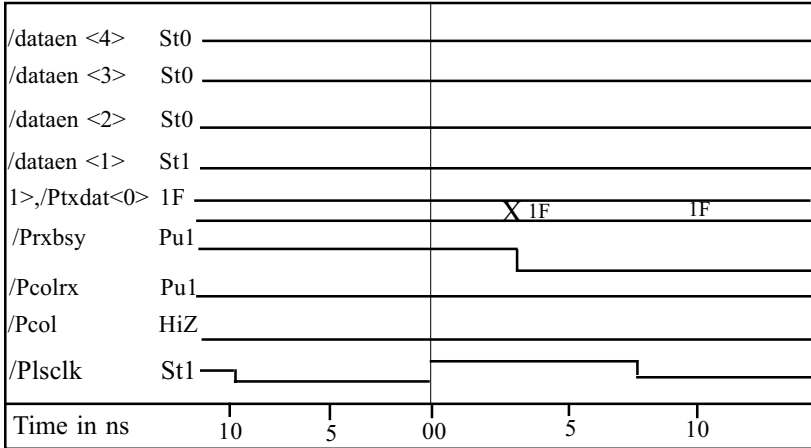
**Clock to Pcolrx and Pcol active when  
a collision occurs**



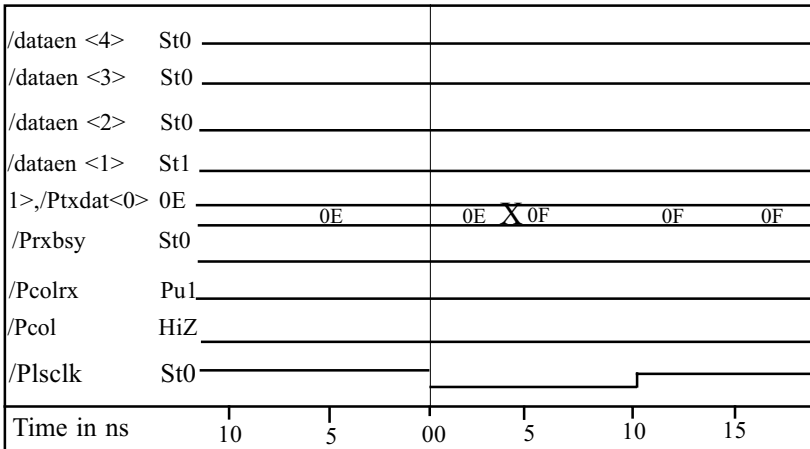
**Clock to Prxbsy high and  
byway data disable at end of packet**



## Clock to Prxbsy low and by way data enable at beginning of packet

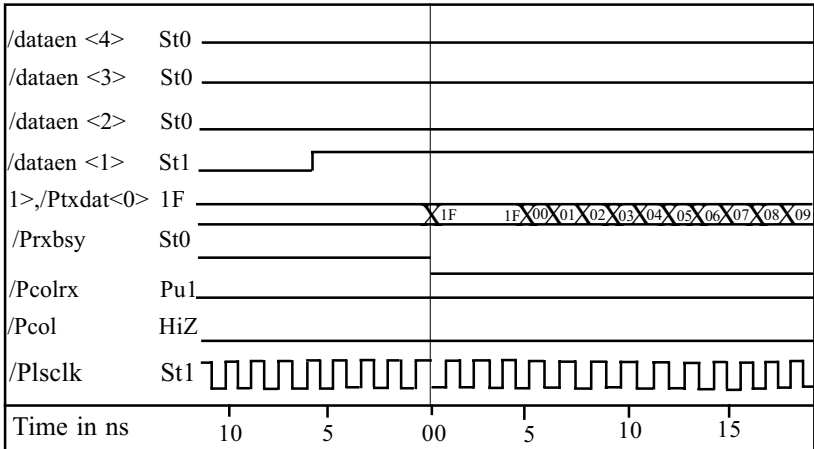


## Clocking of byway data

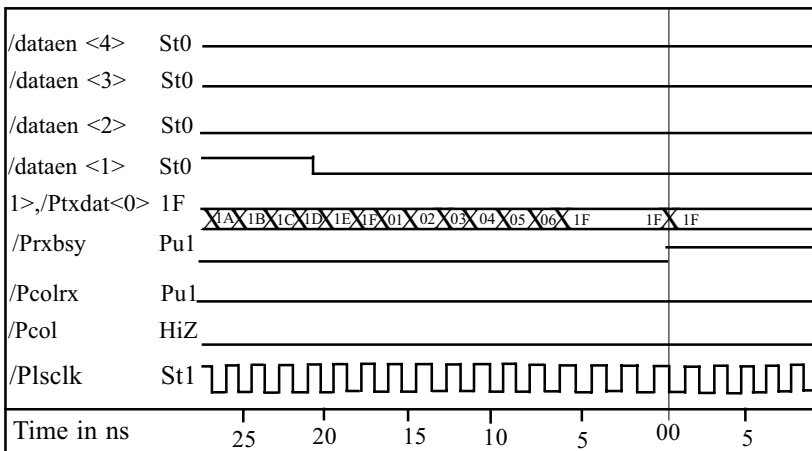




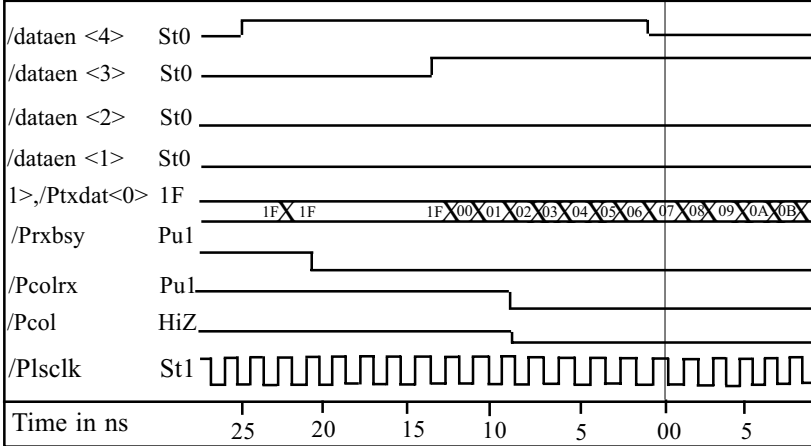
**Beginning of packet  
(1 channel starts transmission)**



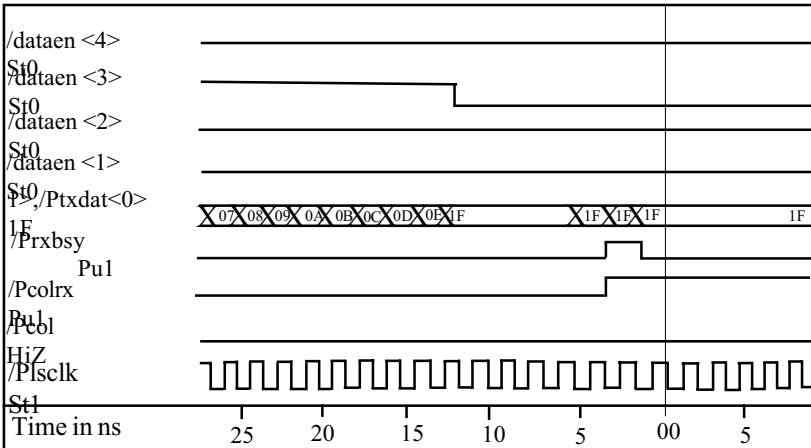
**End of packet  
(1 channel ends transmission)**



**Beginning of collision  
(two channels try to transmit simultaneously)**



**End of collision  
(the collided channels ceased transmission)**



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## Electrical Specification

<i>V<sub>cc</sub></i>	<i>+5V ± 10%</i>
<i>V<sub>dd</sub> (Core)</i>	<i>+5V ± 10%</i>
<i>I<sub>cu</sub></i>	<i>50 mA (typical) 60 mA (max)</i>
<i>GND and GND<sub>c</sub></i>	<i>0V</i>
<i>Input - Low</i>	<i>&lt; 0.7V</i>
<i>Input - High</i>	<i>≥ 1.8V</i>
<i>Output - Low</i>	<i>&lt; 0.6V</i>
<i>Output - High</i>	<i>≥ 2.6V</i>
<i>Input - Load</i>	<i>5 gates</i>
<i>LSCLK</i>	<i>25 Mhz</i>

### Operating Temperature:

Range 0°C - 70°C

Humidity 90% (Non condensing)

### Storage Temperature:

Range -10°C - +80°C

Humidity 95% (Non condensing)

**Product has to be used within 6-7 hours after unpacking.**

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